

## High voltage power Schottky rectifier

### Main product characteristics

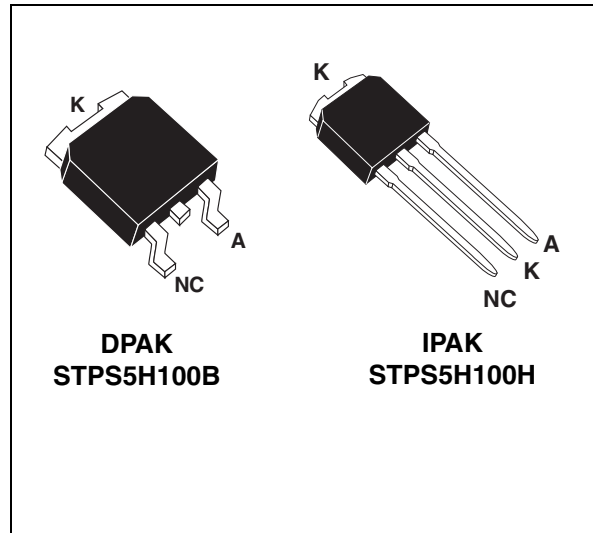
$I_{F(AV)}$	5 A
$V_{RRM}$	100 V
$T_j$ (max)	175° C
$V_F$ (max)	0.61 V

### Features and benefits

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade off between leakage current and forward voltage drop
- Avalanche specification

### Description

This high voltage Schottky barrier rectifier is packaged in DPAK and IPAK, and designed for high frequency miniature switched mode power supplies such as adaptators and on board DC to DC converters.



### Order codes

Part number	Marking
STPS5H100B	S5H100
STPS5H100B-TR	S5H100
STPS5H100H	S5H100H

**Table 1. Absolute ratings (limiting values)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		100	V
$I_{F(RMS)}$	RMS forward voltage		10	A
$I_{F(AV)}$	Average forward current	$T_c = 165^\circ \text{C} \delta = 0.5$	5	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms sinusoidal}$	75	A
$I_{RRM}$	Repetitive peak reverse current	$t_p = 2 \mu\text{s} F = 1 \text{ KHz}$	1	A
$I_{RSM}$	Non repetitive peak reverse current	$t_p = 100 \mu\text{s square}$	2	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1 \mu\text{s} T_j = 25^\circ \text{C}$	7200	W
$T_{stg}$	Storage temperature range		-65 to + 175	°C
$T_j$	Maximum operating junction temperature <sup>(1)</sup>		175	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/ $\mu\text{s}$

1.  $\frac{dP_{Tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

# 1 Characteristics

**Table 2. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	2.5	°C/W

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$			3.5	$\mu\text{A}$
		$T_j = 125^\circ\text{C}$			1.3	4.5
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 5\text{ A}$		0.73	V
		$T_j = 125^\circ\text{C}$			0.57	
		$T_j = 25^\circ\text{C}$	$I_F = 10\text{ A}$		0.85	
		$T_j = 125^\circ\text{C}$			0.66	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.51 \times I_{F(AV)} + 0.02 I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current

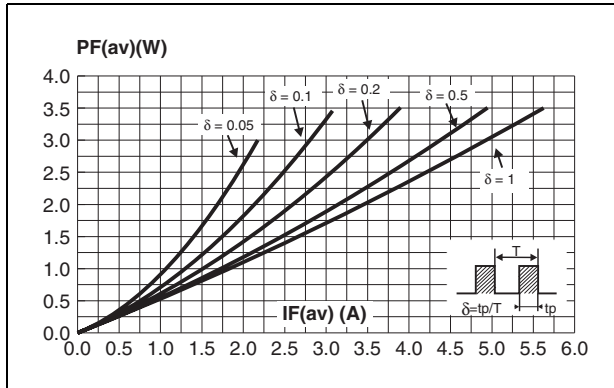


Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )

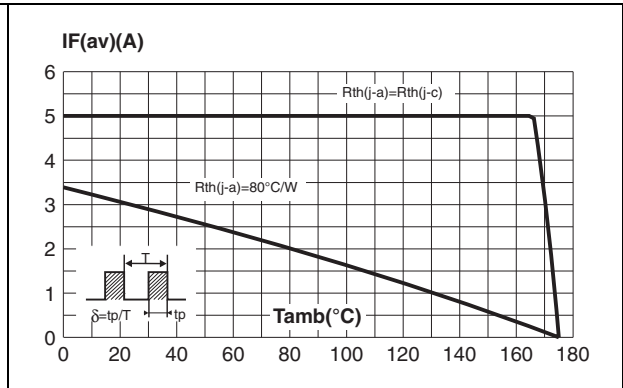


Figure 3. Normalized avalanche power derating versus pulse duration

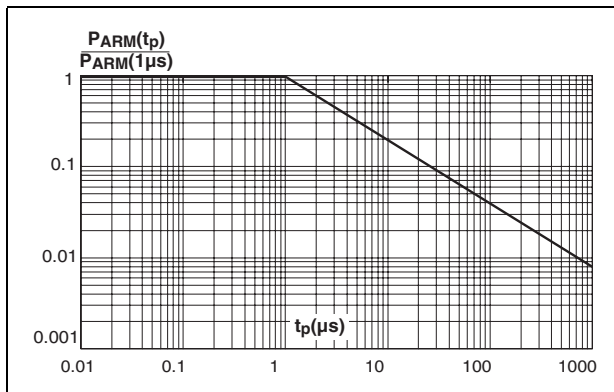


Figure 4. Normalized avalanche power derating versus junction temperature

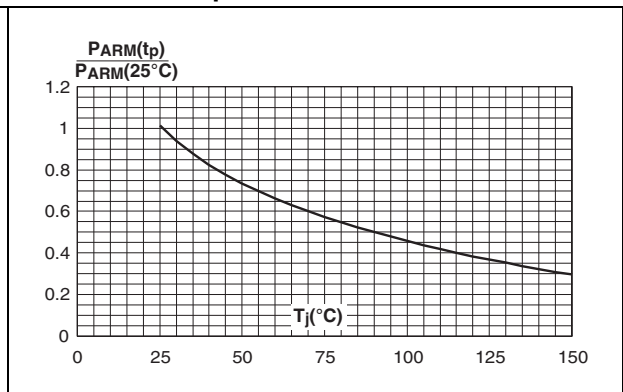


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

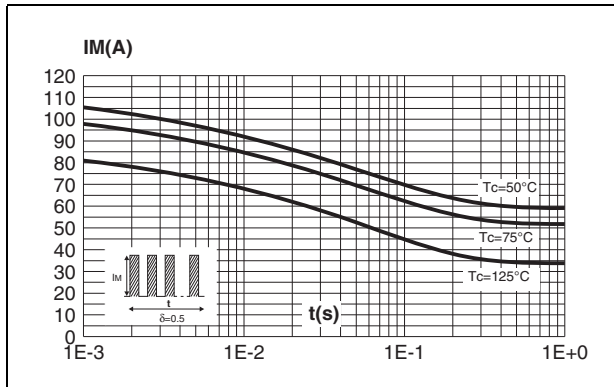
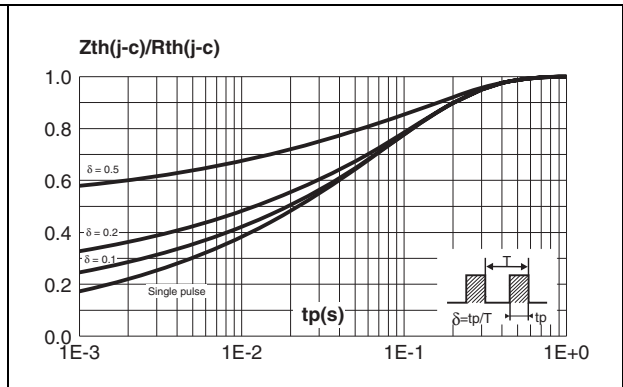
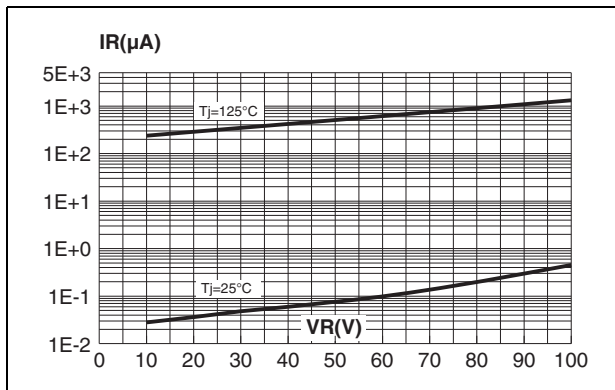


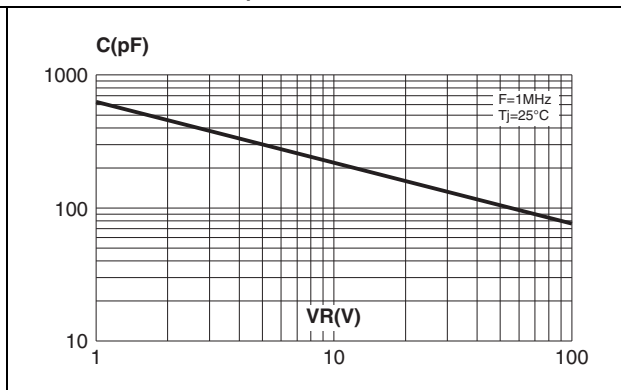
Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



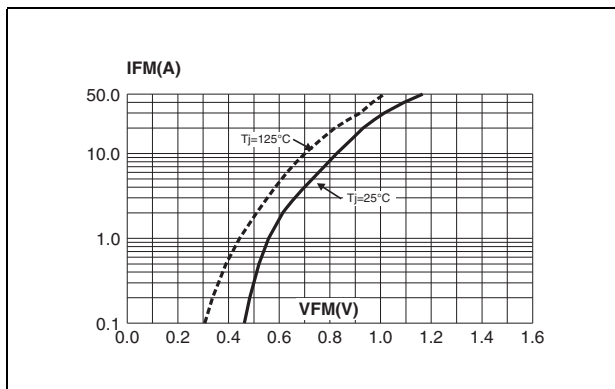
**Figure 7. Reverse leakage current versus reverse voltage applied**



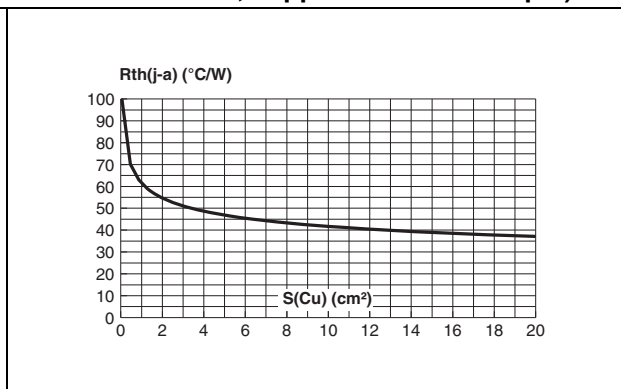
**Figure 8. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 9. Forward voltage drop versus forward current (maximum values)**



**Figure 10. Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board, copper thickness: 35  $\mu m$ )**



## 2 Package information

- Cooling method: by conduction (C)
- Epoxy meets UL94, V0

Figure 11. DPAK dimensions

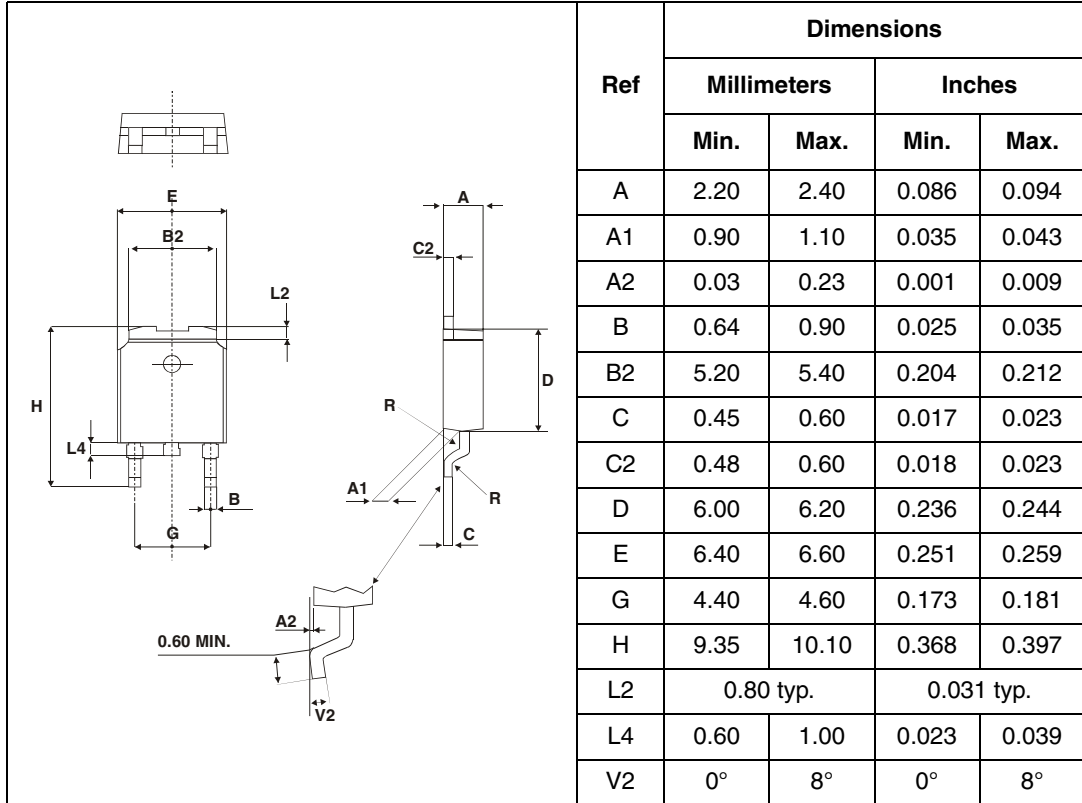
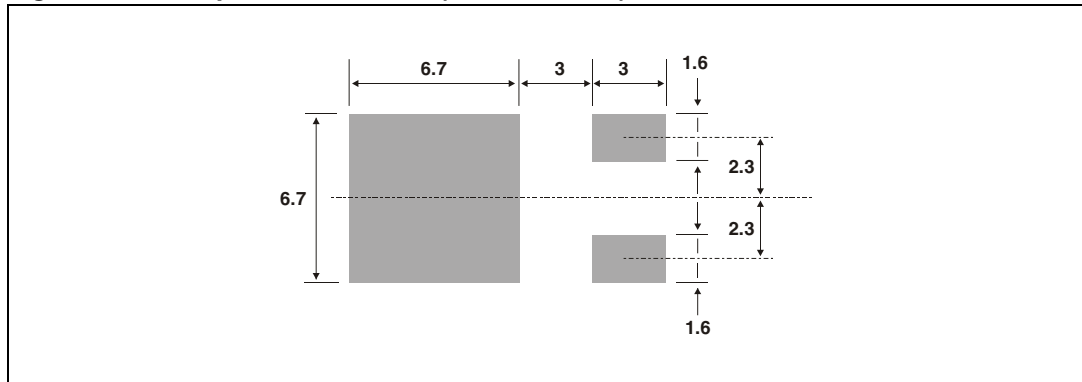
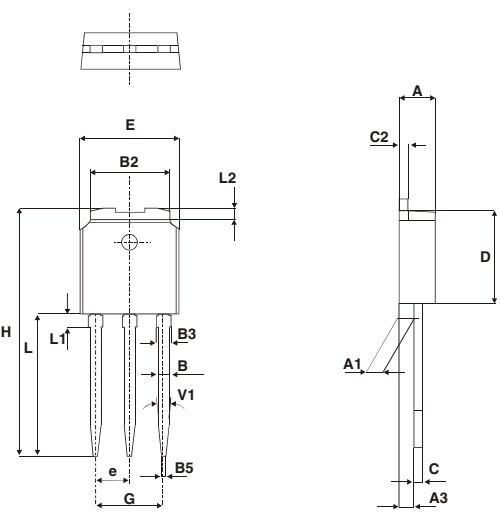


Figure 12. Footprint dimensions (in millimeters)



**Table 4. IPAK Dimensions**



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.094
A1	0.90		1.10	0.035		0.043
A3	0.70		1.30	0.027		0.051
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.212
B3			0.95			0.037
B5		0.30			0.035	
C	0.45		0.60	0.017		0.023
C2	0.48		0.60	0.019		0.023
D	6		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
e		2.28			0.090	
G	4.40		4.60	0.173		0.181
H		16.10			0.634	
L	9		9.40	0.354		0.370
L1	0.8		1.20	0.031		0.047
L2		0.80	1		0.031	0.039
V1		10°			10°	

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### 3 Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS5H100B	S5H100	DPAK	0.30 g	75	Tube
STPS5H100B-TR	S5H100			2500	Tape and reel
STPS5H100H	S5H100H	IPAK	0.40 g	75	Tube

### 4 Revision history

Date	Revision	Description of changes
Jul-2003	6B	Last issue.
03-Nov-2005	7	DPAK footprint dimensions updated.
15-Feb-2006	8	ECOPACK statement added.
05-Mar-2007	9	IPAK package added.

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